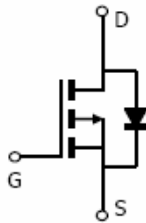
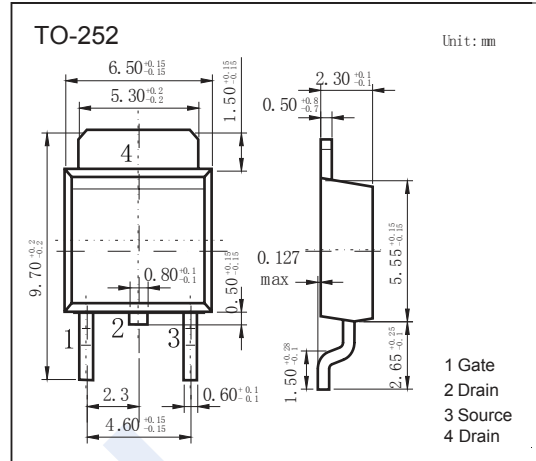


## P-Channel MOSFET

### NDT40P04

#### ■ Features

- $V_{DS} = -40V$
- $I_D = -40 A$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 14m\Omega$  ( $V_{GS} = -10V$ )
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current $T_c = 25^\circ C$	$I_D$	-40	A
		-25	
Pulsed Drain Current	$I_{DM}$	-50	
Power Dissipation	$P_D$	80	W
Derating factor		0.53	W/ $^\circ C$
Single Pulse Avalanche Energy (Note.1)	EAS	544	mJ
Thermal Resistance Junction- to-Case	$R_{thJC}$	1.88	$^\circ C/W$
Junction Temperature	$T_J$	175	$^\circ C$
Junction Storage Temperature Range	$T_{stg}$	-55 to 175	

Note. 1: EAS condition:  $T_J = 25^\circ C$ ,  $V_{DD} = -20V$ ,  $V_G = -10V$ ,  $L = 1mH$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 33A$

## P-Channel MOSFET

### NDT40P04

#### ■ Electrical Characteristics Ta = 25°C

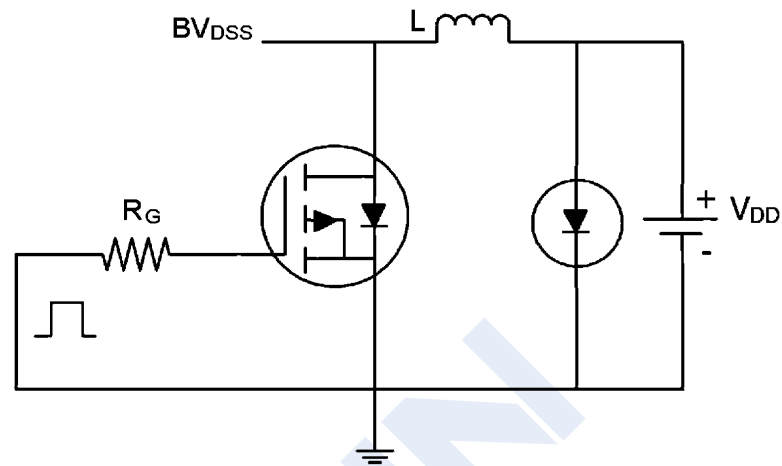
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =-250 μ A, V <sub>GS</sub> =0V	-40			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V			-1	μ A
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μ A	-1.5		-3	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-12A			14	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-12A	34			S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V, f=1MHz		2960		pF
Output Capacitance	C <sub>oss</sub>			370		
Reverse Transfer Capacitance	C <sub>rss</sub>			310		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, I <sub>D</sub> =-12A		12		nC
Gate Source Charge	Q <sub>gs</sub>			14		
Gate Drain Charge	Q <sub>gd</sub>			15		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>DD</sub> =-20V, I <sub>D</sub> =-20A V <sub>GS</sub> =-10V, R <sub>G</sub> =3Ω		10		ns
Turn-On Rise Time	t <sub>r</sub>			18		
Turn-Off DelayTime	t <sub>d(off)</sub>			38		
Turn-Off Fall Time	t <sub>f</sub>			24		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =-20A, di/dt=100A/us, T <sub>J</sub> =25°C		40		nC
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			42		
Maximum Body-Diode Continuous Current	I <sub>S</sub>				-40	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-20A, V <sub>GS</sub> =0V			-1.2	V

Note : Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.

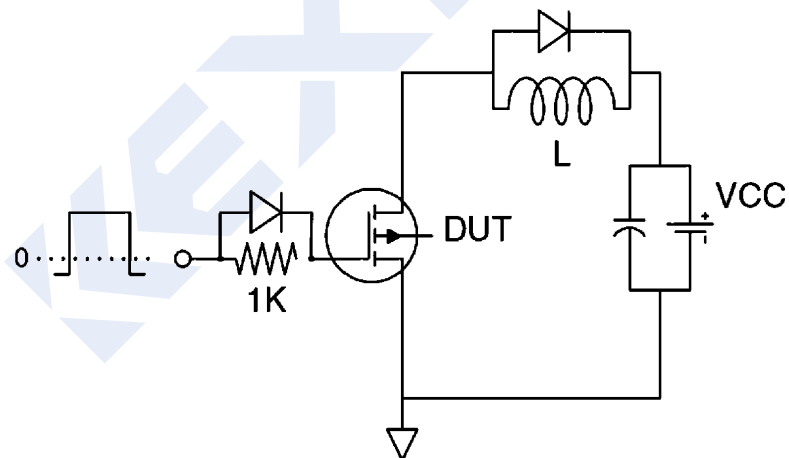
## P-Channel MOSFET NDT40P04

### ■ Test Circuit

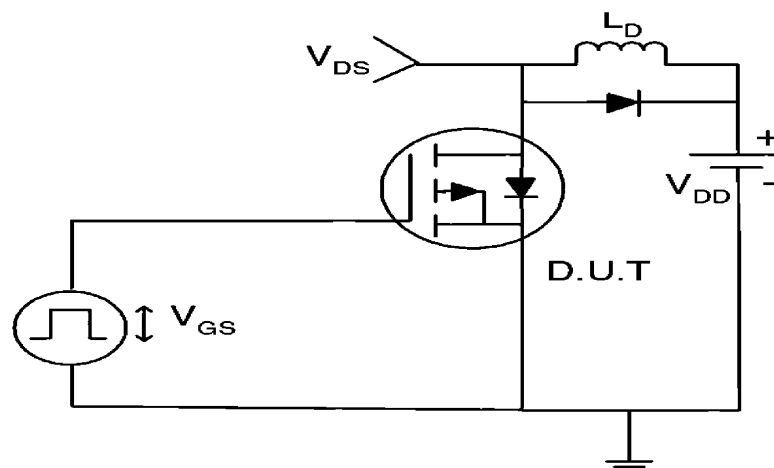
#### 1) $E_{AS}$ Test Circuit



#### 2) Gate Charge Test Circuit



#### 3) Switch Time Test Circuit



## P-Channel MOSFET NDT40P04

■ Typical Characteristics

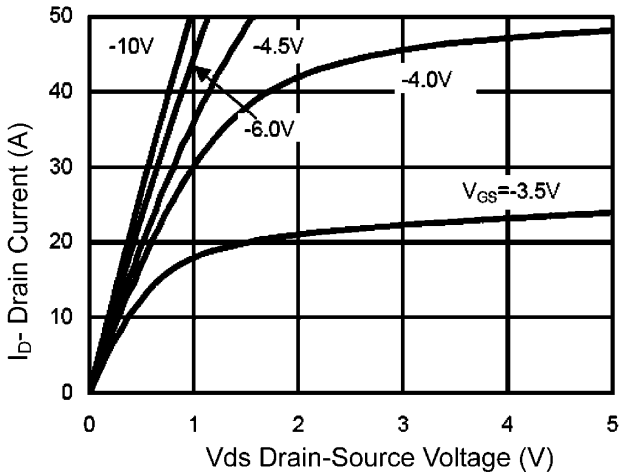


Figure 1 Output Characteristics

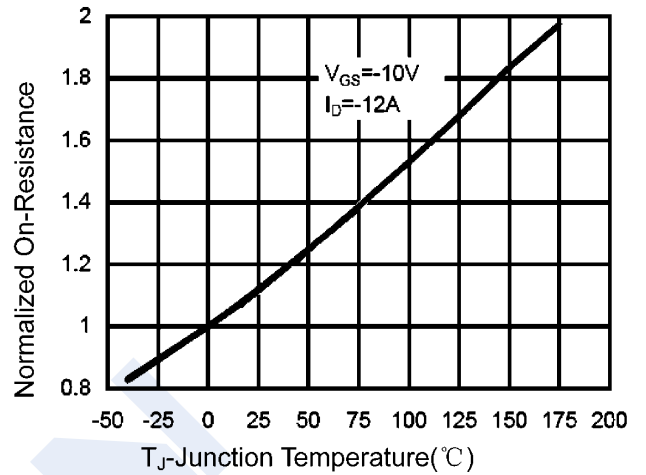


Figure 4 Rds(on)-Junction Temperature

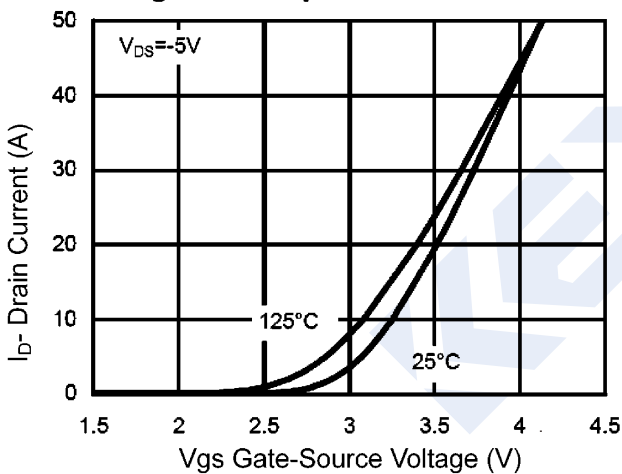


Figure 2 Transfer Characteristics

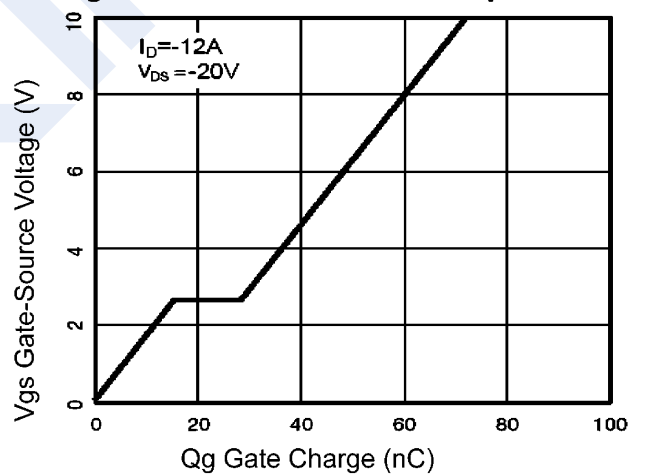


Figure 5 Gate Charge

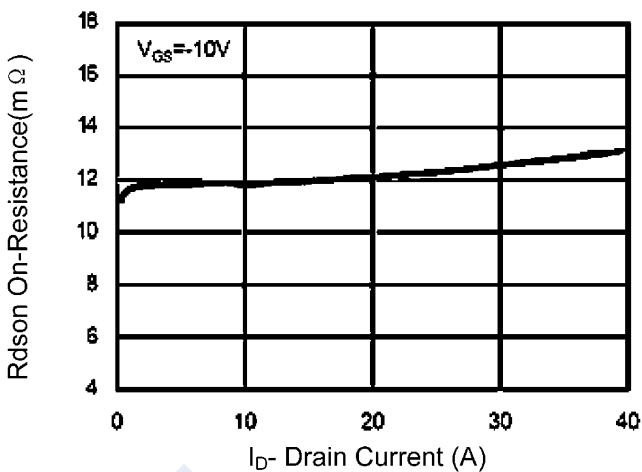


Figure 3 Rds(on)- Drain Current

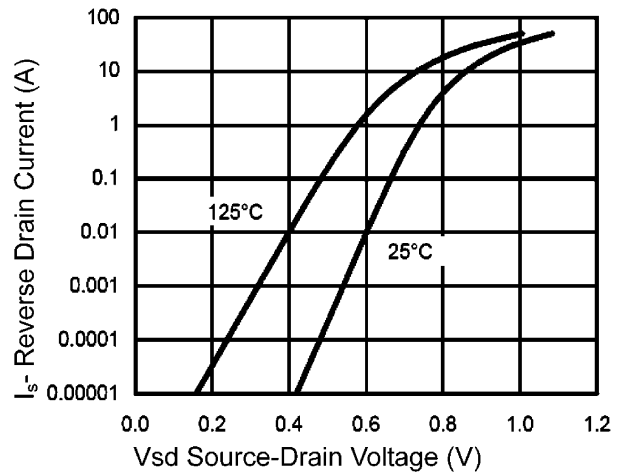


Figure 6 Source- Drain Diode Forward

### P-Channel MOSFET NDT40P04

■ Typical Characteristics

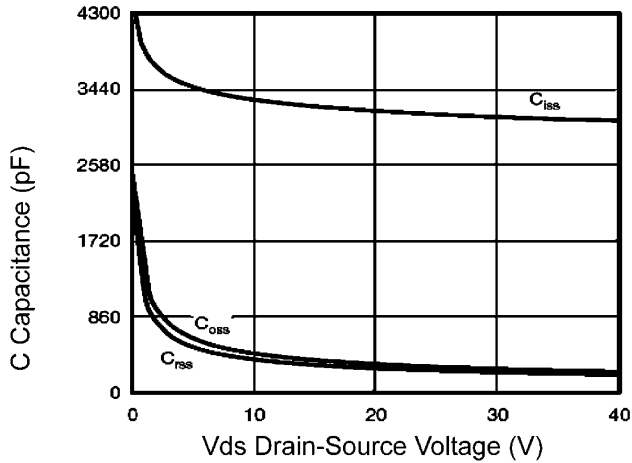


Figure 7 Capacitance vs Vds

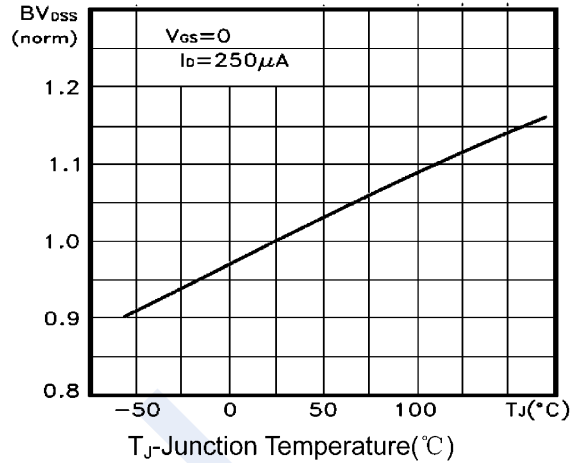


Figure 9  $BV_{DSS}$  vs Junction Temperature

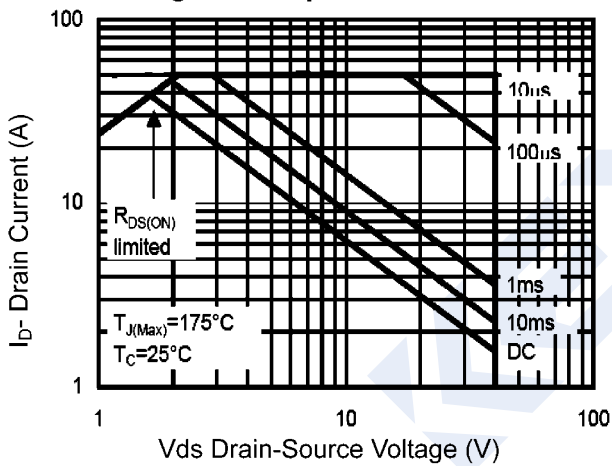


Figure 8 Safe Operation Area

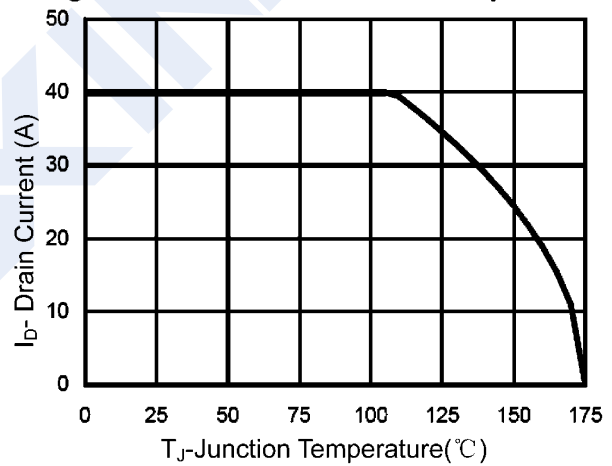


Figure 10  $I_D$  Current Derating vs Junction Temperature

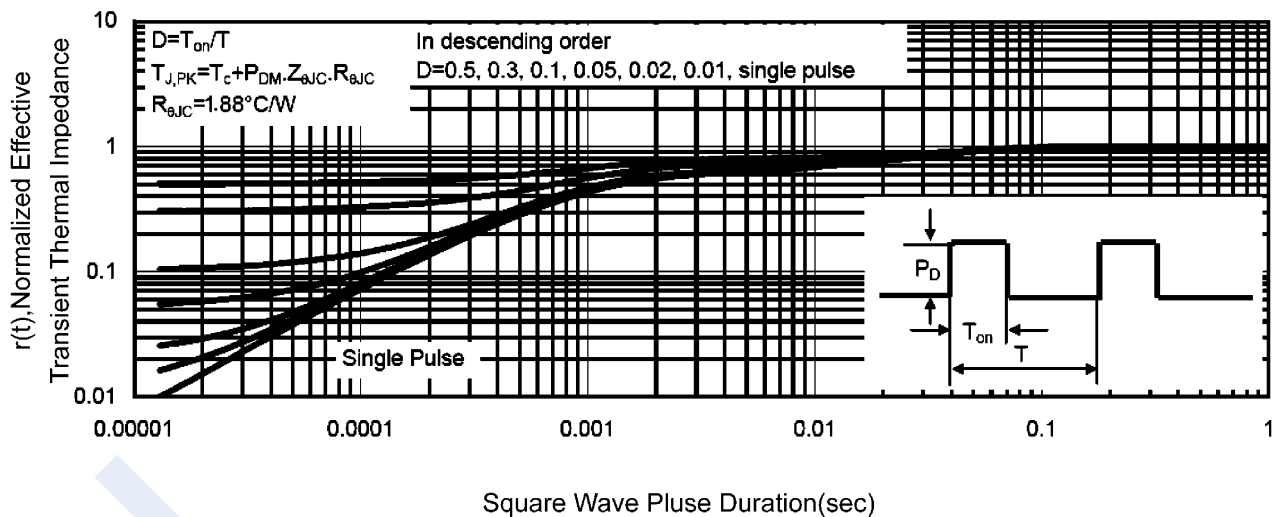


Figure 11 Normalized Maximum Transient Thermal Impedance